BA 908

1 Mil Polyimide Film with High Temperature Adhesive



Description:

BA 908 is constructed to fill the requirements of high-performance thermoplastic Polyimide backing materials. It is designed to fill the need of non-silicone adhesive gold finger connecter wave solder protection and works well for both solvent and water-based fluxes. BA 908 fills the various needs in electronic assembly and electrical insulation applications.

Features & Benefits:

- Acrylic adhesive can be thermoset
- Backing meets MIL-P-46112B
- ESD control
- Impact and abrasion resistant
- Meets Requirements of ASTM E595
- Outstanding resistance to cut through

Applications:

Electronic assembly | Electrical insulation | Fill the need of non-silicone adhesive gold finger connecter wave solder protection

Construction/ Typical Properties	Value	
Color(s):	Amber	
Adhesive:	Acrylic	
Backing:	Film-Polyimide	
Elongation at Break:	50%	
Dielectric Strength:	7,000 volts	
Direct Electrolytic Corr.:	1.0	
Insulation Class:	155 (°C)	
	Imperial	Metric
Adhesive Thickness:	1.5 mils	38 µm
Backing Thickness:	1 mil	25 µm
Total Thickness:	2.5 mils	64 µm
Tensile Strength:	30 lb/in	53 N/cm
Adhesion to Steel:	30 oz/in	3.3 N/cm
Operating Temperature:	-20 to +350 °F	-29 to +177 °C

The physical properties listed above are typical values and are not to be construed as specifications. Our suggestions and recommendations for use are based on tests we believe to be reliable. Bron Aerotech does not warrant that the product is fit for any particular purpose. Purchaser must determine suitability of the product for the intended use. Bron Aerotech, Inc. assumes no liability for claims beyond the replacement value of our product proved to be defective. Manufactured for and distributed by Bron Aerotech.

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